

POLYCRYSTALLINE DIAMOND COMPOUND

HYPREZ Diamond Compounds using polycrystalline diamond helps achieve high surface quality on crystal material types, sapphire domes and other 3D shapes. Diamond sizes from 50 nm - 30 microns available.



POLISHING SLURRY & PADS HYPREZ POLISHING SLURRIES & PADS

Customized to the type of material being polished and are available in a variety of configurations to suit your needs.



CONTACT US

ENGIS Corporation 105 West Hintz Road Wheeling, Illinois 60090 info@engis.com WWW.ENGIS.COM SYSTEMS AND SOLUTIONS FOR POLISHING PRECISION OPTICS AND ADVANCED MATERIALS



REDUCE COSTS
REDUCED PROCESSING TIME
IMPROVE SURFACE QUALITY
EDGE TO EDGE FLATNESS

EVG SERIES PRECISION GRINDING MACHINES

EVG Series Precision Grinding Machines and grinding wheels offer a first step process to remove damage from slicing, improve flatness, and to reach your desired thickness while improving surface quality. The EVG Series offers a compact design, robust build and advanced PLC controls and monitoring functions. Options:

- Max. substrate size: up to 300 mm
- Wheel dressings: manual or auto
- Substrate thickness measurement & control
- Wheel load monitoring control



LAPPING & POLISHING SYSTEMS



Lapping and polishing machines are available in a range of sizes and advanced features, suitable for R&D, small batch production or full output production.



Features include, automatic slurry delivery, variable in cycle pneumatic pressure control and plate temperature control.

Plate flatness and condition can easily be controlled by an automated facing system, which can also be used to create variable groove patterns for optimum contact between plate and part..



ADVANCED CONSUMABLES

DIAMOND LAPPING/POLISHING SLURRIES

Our precision grade slurries are available in either water soluble or oil based suspensions. Engis diamond slurries combined with Engis Hyprez composite polishing plates provide optimum performance with excellent surface quality on crystal type materials and semi polishing glass types.

COMPOSITE LAP PLATES

HYPREZ composite plates are a superior alternative to solid metal plates for efficient lapping fundamentally reducing final polishing time and cost especially when utilizing Engis plate facing technology. **C250 Lap Plate**

This composite copper lap plate provides high stock removal and is suited for diamond sizes from 3-15 microns for first step lapping.

TX-10A lap Plate

This composite tin plate is ideal for 2nd step of lapping to achieve an optical quality finish, or to dramatically reduce subsequent pitch or pad polishing times.

